

AMENDMENTS

In the Title:

Please replace the title with the following:

-- Adhesive To Attach A Cooling Device To A Thermal Interface --

In the Specification:

Please insert as the first sentence of the specification:

-- This application is a continuation patent application of Application Serial No. 09/158,227, entitled *Application of Pressure Sensitive Adhesive (PSA) to Pre-attach Thermal Interface Film/Tape to Cooling Device*, and filed on September 22, 1998. --

Please replace the paragraph beginning at page 9, line 24 with the paragraph:

Next, thermal interface 102, with PSA strips 104 applied near edges thereof, is attached to a surface 104 of base plate 120 as illustrated in **Figure 5**. The attachment is mainly due to an adhesive surface of PSA 104 that makes contact with surface 140 of base plate 120. Note that PSA 104 is compliant, becoming very thin when thermal interface 102 is pressed and attached to base plate 120 of heat sink 118. Heat may be transferred from the integrated circuit package 116 to the heat sink 118 mainly via heat transfer area 106, demarcated by dotted lines 112 and 114. Heat transfer area 106 is not covered by PSA 104. The vendor of the heat sink may then ship the assembly, including the heat sink 118 with the thermal interface 102 attached thereto, to the manufacturer of the integrated circuit package, for further assembling the integrated circuit package 116 to the assembly.